



Metalon® Conductive Inks for Printed Electronics

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Metalon® HPSC-U335

High Conductivity Silver-Coated Copper Screen Ink

GENERAL INFORMATION

- Particle:** 3-micron silver-coated copper particles (35% w/w Cu)
- Substrates:** Paper, plastics, glass, metals
- Features:**
- Economical pricing
 - High metal loading (87% w/w metal)
 - High conductivity for low temperature curing
 - Excellent water and alcohol resistance
 - Flexible and good adhesion
 - Printing equipment cleans with isopropanol
 - Conductivity can be adjusted with Ag amount
 - Solderable

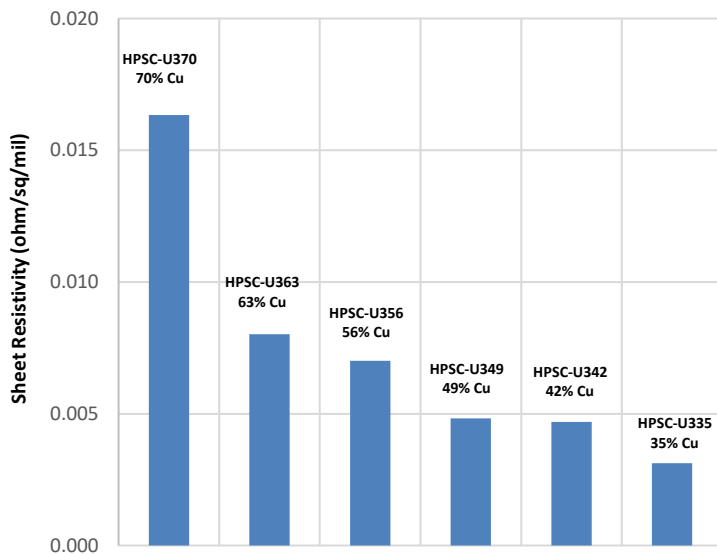
THERMAL CURE DATA

Cure Temperature ¹ (°C)	Cure Time (minutes)	Volume Resistivity ² (Ω-cm)	Sheet Resistivity ² (Ω/sq/mil)
80	120	6.1E-05	0.024
100	120	2.1E-05	0.008
120	30	1.1E-05	0.004
140	15	0.8E-05	0.003
150	15	0.8E-05	0.003
175	15	0.8E-05	0.003
200	10	0.8E-05	0.003

¹Pre-cure drying at 140C for 10 minutes for cure ≥ 175C

²Typical value (#10 drawdown and 25% porosity - typical dried coating 0.013g/cm²)

HPSC-U Silver-coated copper inks (cured at 140C)



Physical Properties	General description.....	Ag-coated Cu particle ink
	Viscosity (typical values)...	187,000 cP at 10 sec ⁻¹ 61,000 cP at 100 sec ⁻¹
	Specific gravity.....	4.5
	Particle size.....	D50 - 3 microns
	Metal content.....	87% w/w
Storage and Printing	Storage.....	Room temperature
	Shelf life.....	> 6 months
	Cleaning solvent.....	Isopropanol
	Screen mesh material.....	Stainless steel or polyester
	Screen mesh count.....	325 to 80 wires per inch
Shipping and Packaging	MOQ - 100 grams	

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Contact us today to learn more.
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